

January 14, 2001

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application of**  
Serial No.: 09261,681 3/3/99

**GEORGE WONG**

**A FILL PATTERN IN KERF AREAS TO PREVENT  
LOCALIZED NON-UNIFORMITIES OF INSULATING  
LAYERS AT DIE CORNERS ON SEMICONDUCTOR  
SUBSTRATES**

**PRELIMINARY AMENDMENT**

Dear Sir:

This is a preliminary amendment for the above referenced Divisional Patent Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on January 16, 2001.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

1/16/01

**PLEASE AMEND THE SPECIFICATION AS FOLLOWS:**

After the title, insert -- This is a division of Patent Application serial number 09261,681, filing date 3/3/99, A Fill Pattern In Kerf Areas To Prevent Localized Non-Uniformities Of Insulating Layers At Die Corners On Semiconductor Substrates, assigned to the same assignee as the present invention.

**REMARKS**

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,



STEPHEN B. ACKERMAN, REG. NO. 37,761